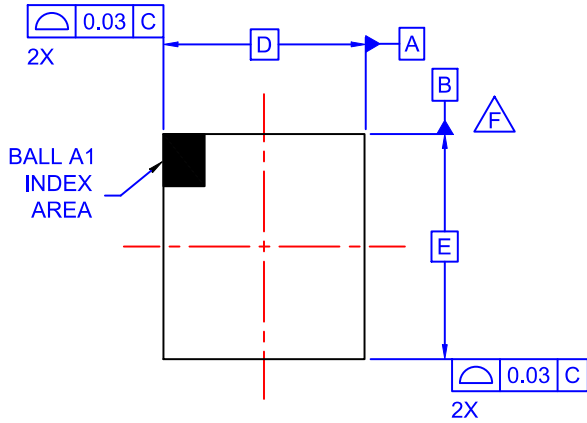


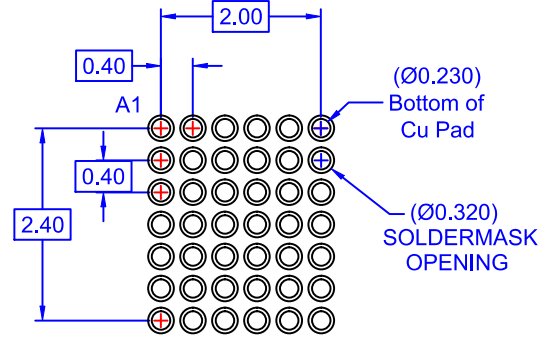


**WLCSP42 2.78x3.06x0.65**  
CASE 567TY  
ISSUE O

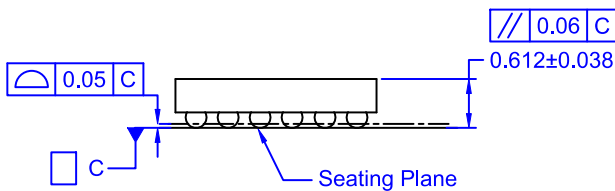
DATE 31 MAR 2017



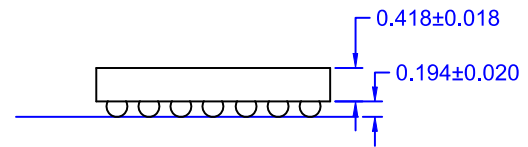
TOP VIEW



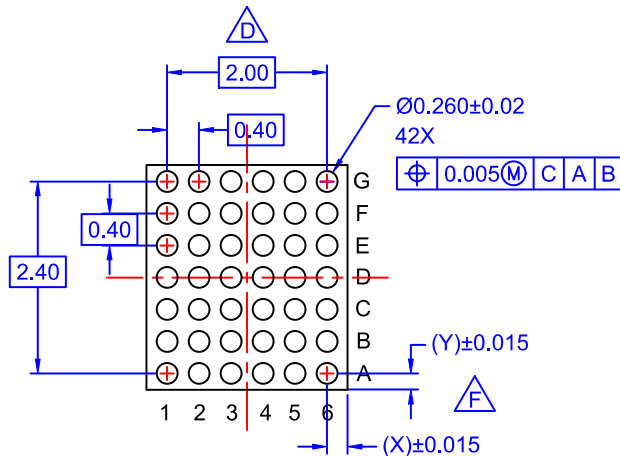
RECOMMENDED LAND PATTERN  
(NSMD TYPE)



END VIEW



SIDE VIEW



BOTTOM VIEW

NOTES

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 2009.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 612 ± 38 MICRONS (574-650 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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<b>DESCRIPTION:</b>	<b>WLCSP42 2.78x3.06x0.65</b>	<b>PAGE 1 OF 1</b>

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